

ABSTRACT OF THE DISCLOSURE

Peeling between a molding resin and a substrate is prevented to improve the quality of a semiconductor device. A film substrate capable of being deformed following shrinkage upon curing of a molding resin and having plural partitioned device areas is provided. Then, a block molding is performed so as to cover the plural device areas in a lump on a chip bearing surface side of the film substrate. Thereafter the film substrate is subjected to dicing wherein a cutting blade is advanced toward a block molding portion to divide the film substrate device area by device area in accordance with a down cutting method, whereby peeling of the substrate in the dicing work can be prevented.